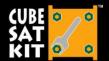




# **Development Opportunities within** the CubeSat Kit Architecture

Andrew E. Kalman, Ph.D.





## **Outline**



Part I: Historical Overview & Observations

Part II: Internal Module Stacking

Part III: Underutilized Volume

Part IV: External Payloads

Part V: Connectors

Part VI: Mass Reduction

Part VII: Software

Part VIII: The Future

## **Overview & Observations**



- About to deliver 100<sup>th</sup> Flight Module & Development Board (December 2003 – April 2008)
- 1U & 3U configurations most popular, 2U gaining ground
- Solid-wall structures now deprecated due to inherent mass penalty. Still available by special order
- New CubeSat Kit 3D CAD models online
- Popular third-party compatible offerings:
  - Clyde Space EPS & solar panels
  - HCC-Embedded EFFS-THIN FAT file system
  - StenSat Group VHF/UHF radio
- Predict up to 4 CubeSat Kit-based nanosatellites to be launched in 2008
- CubeSat mass limit more critical than volume limit





# Part I (cont'd)



- Customers often:
  - Want to model
  - Have aggressive schedules
  - Ask lots and lots of questions
  - Appreciate off-the-shelf availability
  - Are buying from multiple, specialized vendors
  - Often have little or no previous experience in space
  - Benefit from the dedicated Dev Board for development
  - Encounter a non-trivial learning curve for embedded programming









# Part I (cont'd)



- Sometimes, customers:
  - Underestimate "real" costs and production times
  - Still spend a lot of time in the planning stages
  - Read too much into specifications (or a lack thereof)
  - Do not fully appreciate the beauty of the CubeSat specification
  - Want to roll their own solutions when a similar one is already available
  - Fail to take advantage of various CubeSat Kit architectural features
  - Underestimate how much software is required, and how much functionality can be accomplished by a lowly 16-bit microcontroller

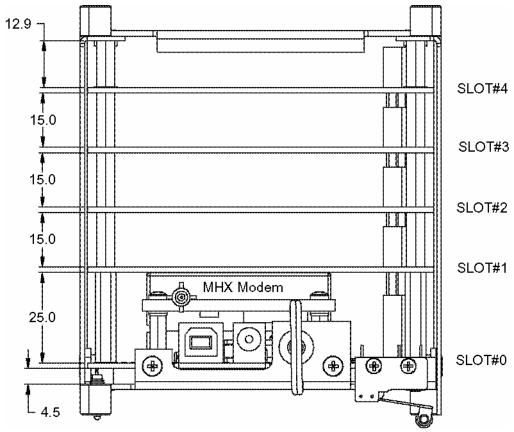


## **Internal Module Stacking**



Internal modules stacked with 15mm + (n x 10mm) between

PCBs:



Typical layout of internal modules in the CubeSat Kit. Minimum inter-PCB distance with CubeSat Kit Bus connectors is 15mm. Pre-release Rev B structure shown.

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# Part II (cont'd)









A selection of CubeSat Kitcompatible internal modules under development at Stanford's SSDL.

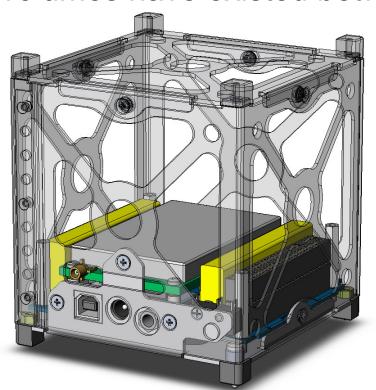
Some multi-level component stacking present. Note low utilization of available 90 x 96 x 15mm volume. Functionality of multiple modules can be combined into a single module.

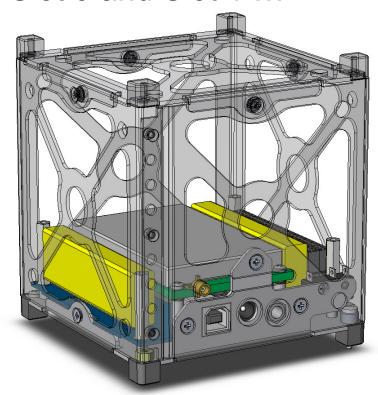


### **Underutilized Volume**



 Ever since first production CubeSat Kit, two underutilized volumes have existed between Slot 0 and Slot 1 ...





Underutilized volumes in Rev D skeletonized CubeSat Kits. Each volume lies above Slot 0 (where the FM430 resides) and below Slot 1. Shown with MHX transceiver module in place, consistent with Slot 1 located 25mm above Slot 0.





# Part III (cont'd)



Specifications of underutilized volumes:

location	Slot 1 @	approx. dimensions <sup>1</sup>	approx. volume
Left	15mm	72 x 15 x 13mm	14cc
	25mm	72 x 15 x 23mm	25cc
Right	15mm	80 x 12 x 11mm	11cc
	25mm	80 x 12 x 21mm	20cc

- Possible applications:
  - Beacon
  - Batteries
  - Cold gas tanks
  - DTMF decoder
  - Secondary radio(s)
  - Accelerometers & magnetometers

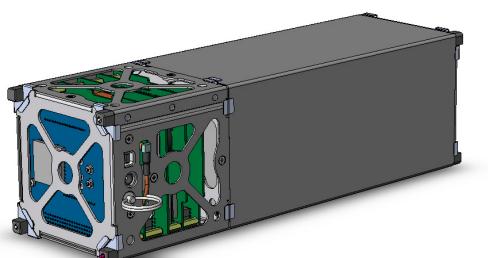
 Dimensions assume no components on underside of Slot 1 module (I.e. smooth underside of Slot 1 PCB in affected areas).



## **External Payloads**

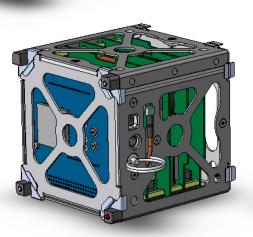


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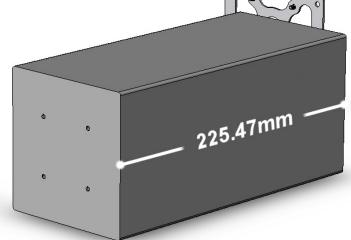


3U CubeSat Kit constructed from a single 1U skeletonized CubeSat Kit (w/ C&DH, radio, EPS & internal payloads) and a 2U external payload (100 x 100 x 225 mm).

Total length is 340.50 mm.



Don't leave Earth without it



### **Connectors**



- The CubeSat Kit Bus uses PC/104-style connectors
- Benefits:
  - High current
  - High reliability
  - Readily available
  - Multiple stacking heights

- Any number of rows available
- Height-extendable in 10mm increments
- On 0.100" (2.54mm) centers, easy to route
- Low impact on PCB real estate (stackthrough)
- Drawbacks:
  - Relatively large (16cc per 104 pins)
  - Relatively heavy (16g per 104 pins)
  - Minimum inter-module (i.e. stacking) spacing of 15mm
  - Not all modules need all pins, yet all pins are carried through





# Part V (cont'd)

Don't leave Earth without it



#### CubeSat Kit Bus Connectors

-CTS MHX -DSR MHX 35 36 -RTS MHX S1 35 36 S1 -DTR MHX S2 37 38 S2 TXD MHX SDA SYS SDA SYS SCL SYS 41 42 VBACKUP S5 41 42 S5 res. 45 46 res. USER0 47 48 USER1 USER2 USER4 51 52 USER5 USER10 51 52 USER11	SENSE T +5V_SW	P5.7 P5.5 P5.3 P5.1 P4.7 P4.5 P4.3 P4.1 P3.7 P3.5 P3.3 P3.1 -FAULT SENSE -RESET OFF VCC +5V SW -CTS MHX -DSR MHX TXD MHX TXD MHX SDA SYS SCL SYS res. USER0 USER0	1 3 5 7 9 11 13 15 7 12 22 22 23 33 33 33 41 43 47 49	38 40 42 44 46 48 50	P5.6 P5.4 P5.2 P5.0 P4.6 P4.4 P4.2 P4.0 P3.6 P3.4 P3.2 P3.0 VREF+ VEREF+ VREF- +5V USB -RST MHX -RTS MHX -RTS MHX RXD MHX VBACKUP res. res. USER1 USER1	+5V_USB	AGND	S3 S4 S5 VBATT USER6 USER8	1 3 5 7 9 11 13 15 17 21 22 27 29 31 35 37 41 43 47 49	38 40 42 44 46 48 50	P6.6 P6.4 P6.2 P6.0 P1.6 P1.4 P1.2 P1.0 P2.6 P2.4 P2.2 P2.0 +5V VCC SYS GND GND S0 S1 S2 S3 S4 S5 VBATT USER7	+5V VCC_SY	S
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CubeSat Kit Bus Connectors. Rev C (104-pin bus) shown.





# Part V (cont'd)



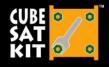
- Some customers taking advantage of architectural features:
  - EPS that use +5V\_USB to charge batteries
  - Clyde Space allocating high-voltage bus to pair of USER pins for one particular end-user
  - Next revision of StenSat VHF/UHF radio to have +5V direct UART interface via TXD\_MHX & RXD\_MHX
- Un(der)utilized CubeSat Kit Bus features:
  - +5V\_USB to power multiple processors via USB "umbilical"
  - Unused S[5..0] pairs for non-standard power bus, etc.
  - \*\_MHX for direct [+5V,0] interface to radio in MHX slot
  - VBACKUP for flexible location of RTC chip backup battery
  - SENSE and -FAULT signals for supervisor



### **Mass Reduction**



- Rev D structures are probably close to the minimum mass for an Aluminum-based approach
- PCBs and connectors may provide biggest (and easiest) mass reductions. Suggestions:
  - Go from 0.062" (1.5mm) to 0.031" (0.75mm) PCBs wherever possible:  $\Delta_m$  = -16g per 85cm² of PCB real estate. Module, daughterboard-on-module and solar panel PCBs are prime candidates
  - Combine multiple modules into one:  $\Delta_m$  = -16g per 104 pins of CubeSat Kit Bus Connectors saved. Side-effect of more efficient module volume utilization
  - "Manage the reach" of each particular CubeSat Kit Bus signal in successively higher Slots within the CubeSat Kit. Recommend that all module PCBs be laid out for full 104-pin pinout, however
  - For external payloads, fork from CubeSat Kit Bus Connector to payload-specific connector / wiring



## **Software**



- Not enough sharing of software among CubeSat Kit users.
- CubeSat Kit-specific & Pumpkin general software growing to provide libraries of driver-type routines
- HCC-embedded EFFS-THIN for CubeSat Kit:

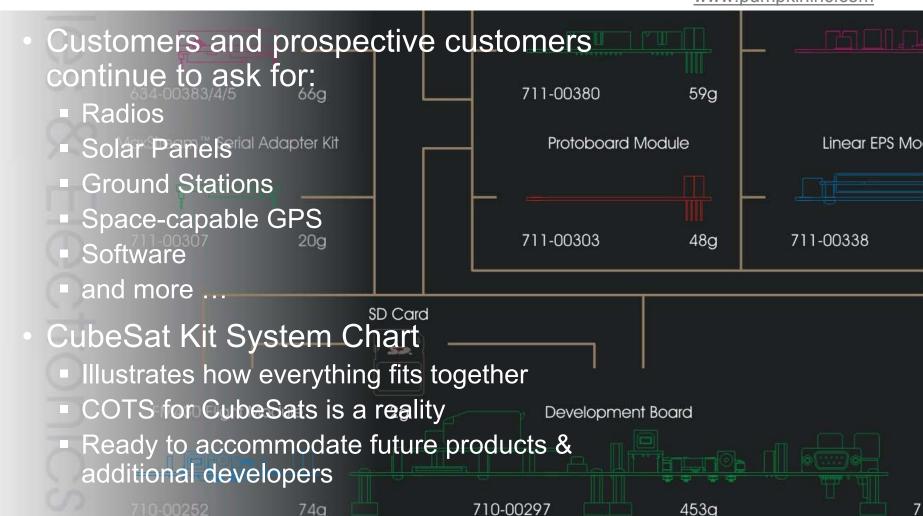
light

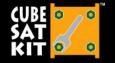
- Can run multiple MSP430s, each with FAT-based SD card for unlimited storage. E.g. for dedicated payload processors
- File-based data exchange among multiple MSP430s
- RTOS-based approach enables simple module sharing:
  - E.g. ADC12 code from Linear EPS runs on FM430 as additional task



### **Future**







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**Q&A Session** 

Thank you for attending!

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# **Notice**

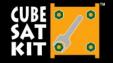


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# **Appendix**



### Speaker information

Dr. Kalman is Pumpkin's president and chief technology architect. He entered the embedded programming world in the mid-1980's. After co-founding Euphonix, Inc – the pioneering Silicon Valley high-tech pro-audio company – he founded Pumpkin, Inc. to explore the feasibility of applying high-level programming paradigms to severely memory-constrained embedded architectures. He is the creator of the Salvo RTOS and the CubeSat Kit. He holds two United States patents and is a consulting professor in the Aero & Astro department at Stanford University. Contact Dr. Kalman at aek@pumpkininc.com.

### Acknowledgements

- Stanford Professors Bob Twiggs' and Jamie Cutler's continued support for the CubeSat Kit, and their inputs on enhancements and suggestions for future CubeSat Kit products, are greatly appreciated.
- Pumpkin's Salvo and CubeSat Kit customers, whose real-world experience with our products helps us improve and innovate.

### Salvo, CubeSat Kit and CubeSat information

More information on Pumpkin's Salvo RTOS and Pumpkin's CubeSat Kit can be found at http://www.pumpkininc.com/ and http://www.cubesatkit.com/, respectively.

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